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Renesas Technology Corp.
Customer Support Dept.
April 1, 2003

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Keep safety first in your circuit designs!

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Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

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HD74HC151

1-of-8-line Data Selector/Multiplexer



ADE-205-449 (Z)

1st. Edition

Sep. 2000

Description

The HD74HC151 selects one of the 8 data sources, depending on the address presented on the A, B and C inputs. It features both true (Y) and complement (W) outputs. The strobe input must be at a low logic level to enable this multiplexer. A high logic level at the strobe forces the W output high and the Y output low.

Features

- High Speed Operation: t_{pd} (Any D to Y or W) = 18 ns typ ($C_L = 50$ pF)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2$ to 6 V
- Low Input Current: 1 μ A max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max ($T_a = 25^\circ\text{C}$)

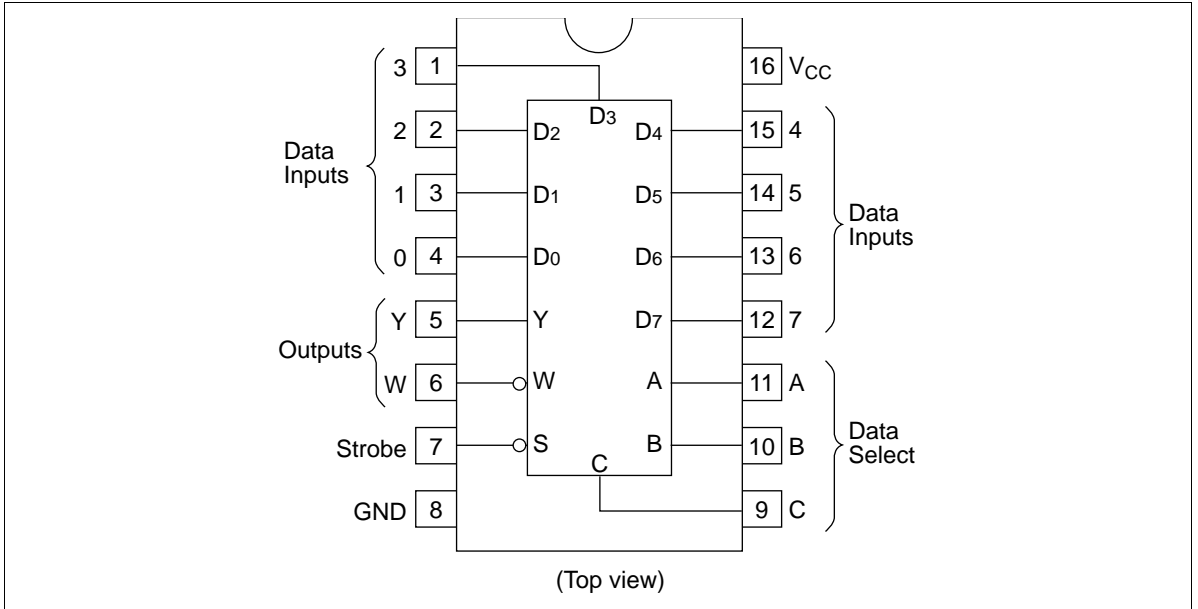
Function Table

Inputs

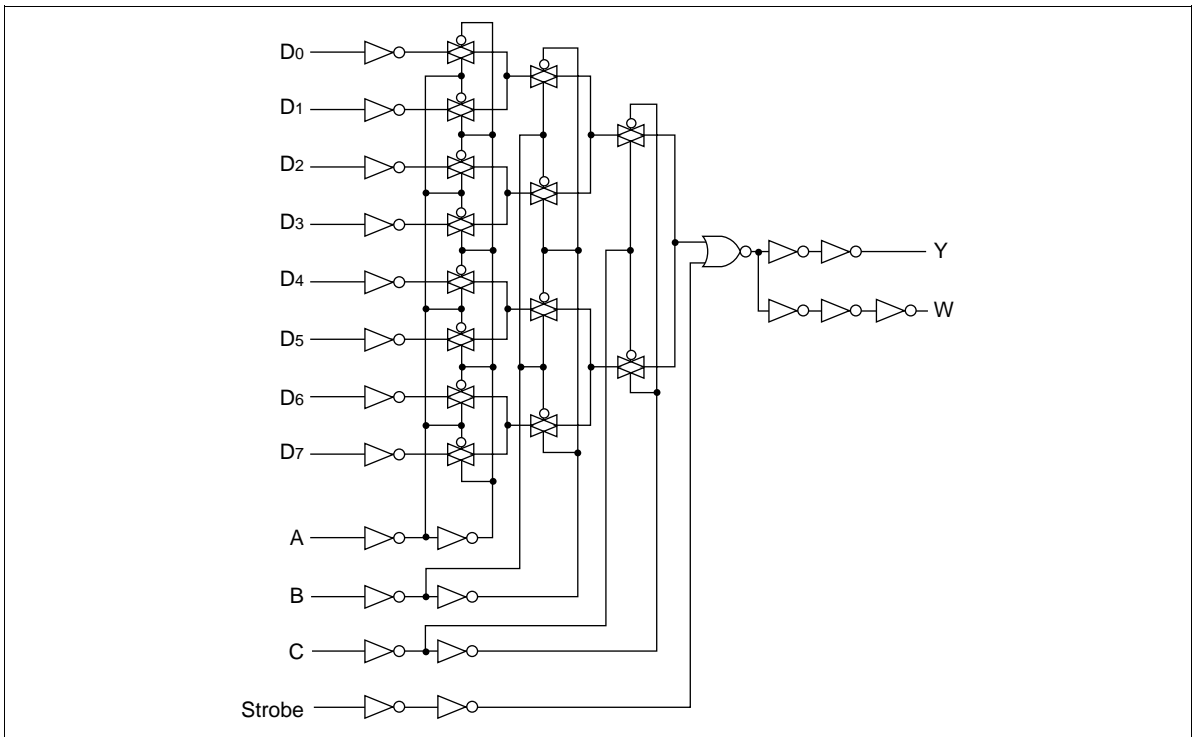
Select				Outputs	
C	B	A	Strobe S	Y	W
X	X	X	H	L	H
L	L	L	L	D_0	$\overline{D_0}$
L	L	H	L	D_1	$\overline{D_1}$
L	H	L	L	D_2	$\overline{D_2}$
L	H	H	L	D_3	$\overline{D_3}$
H	L	L	L	D_4	$\overline{D_4}$
H	L	H	L	D_5	$\overline{D_5}$
H	H	L	L	D_6	$\overline{D_6}$
H	H	H	L	D_7	$\overline{D_7}$

X : Irrelevant

Pin Arrangement



Logic Diagram



DC Characteristics

Item	Symbol	V _{CC} (V)	Ta = 25°C		Ta = -40 to +85°C		Unit	Test Conditions		
			Min	Typ	Max	Min			Max	
Input voltage	V _{IH}	2.0	1.5	—	—	1.5	—	V		
		4.5	3.15	—	—	3.15	—			
		6.0	4.2	—	—	4.2	—			
	V _{IL}	2.0	—	—	0.5	—	0.5	V		
		4.5	—	—	1.35	—	1.35			
		6.0	—	—	1.8	—	1.8			
Output voltage	V _{OH}	2.0	1.9	2.0	—	1.9	—	V	Vin = V _{IH} or V _{IL} I _{OH} = -20 μA	
		4.5	4.4	4.5	—	4.4	—			
		6.0	5.9	6.0	—	5.9	—			
		4.5	4.18	—	—	4.13	—			I _{OH} = -4 mA
		6.0	5.68	—	—	5.63	—			I _{OH} = -5.2 mA
	V _{OL}	2.0	—	0.0	0.1	—	0.1	V	Vin = V _{IH} or V _{IL} I _{OL} = 20 μA	
		4.5	—	0.0	0.1	—	0.1			
		6.0	—	0.0	0.1	—	0.1			
		4.5	—	—	0.26	—	0.33			I _{OL} = 4 mA
		6.0	—	—	0.26	—	0.33			I _{OL} = 5.2 mA
Input current	I _{in}	6.0	—	—	±0.1	—	±1.0	μA	Vin = V _{CC} or GND	
Quiescent supply current	I _{CC}	6.0	—	—	4.0	—	40	μA	Vin = V _{CC} or GND, I _{out} = 0 μA	

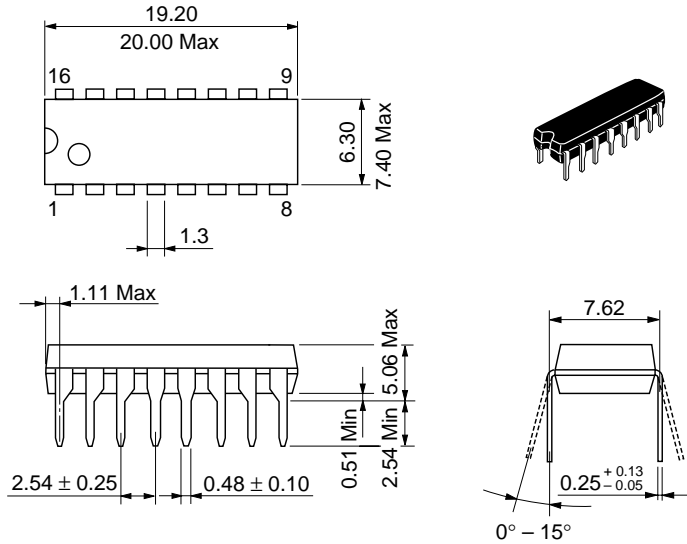
HD74HC151

AC Characteristics ($C_L = 50$ pF, Input $t_r = t_f = 6$ ns)

Item	Symbol	V_{CC} (V)	$T_a = 25^\circ\text{C}$		$T_a = -40$ to $+85^\circ\text{C}$		Unit	Test Conditions	
			Min	Typ	Max	Min			Max
Propagation delay	t_{PLH}	2.0	—	—	205	—	255	ns	A, B or C to Y
time	t_{PHL}	4.5	—	18	41	—	51	A, B or C to W	
		6.0	—	—	35	—	43		
		2.0	—	—	185	—	230		Any D to Y
		4.5	—	18	37	—	46		
		6.0	—	—	31	—	39		
		2.0	—	—	175	—	220		Any D to W
		4.5	—	16	35	—	44		
		6.0	—	—	30	—	37		
		2.0	—	—	170	—	215	Strobe to Y	
		4.5	—	16	34	—	43		
		6.0	—	—	29	—	37		
		2.0	—	—	125	—	155	Strobe to W	
		4.5	—	10	25	—	31		
		6.0	—	—	21	—	26		
		2.0	—	—	115	—	145		
		4.5	—	10	23	—	29		
		6.0	—	—	20	—	25		
		Output rise/fall	t_{TLH}	2.0	—	—	75	—	95
time	t_{THL}	4.5	—	5	15	—	19		
		6.0	—	—	13	—	16		
Input capacitance	C_{in}	—	—	5	10	—	10	pF	

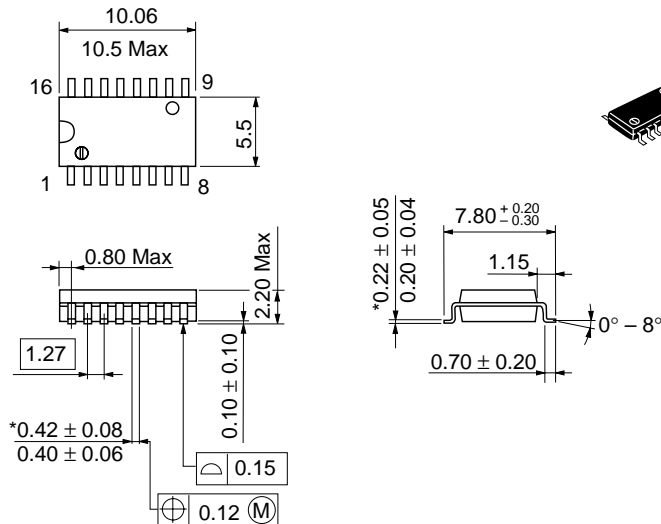
Package Dimensions

Unit: mm



Hitachi Code	DP-16
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	1.07 g

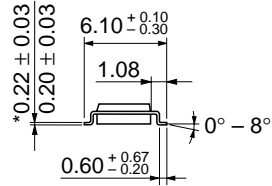
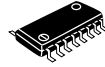
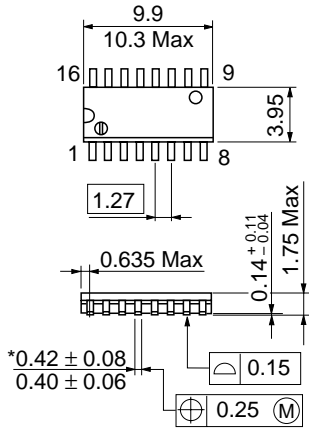
Unit: mm



Hitachi Code	FP-16DA
JEDEC	—
EIAJ	Conforms
Mass (reference value)	0.24 g

*Dimension including the plating thickness
Base material dimension

Unit: mm



*Dimension including the plating thickness
Base material dimension

Hitachi Code	FP-16DN
JEDEC	Conforms
EIAJ	Conforms
Mass (reference value)	0.15 g

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